# **Hex Gate**

The MC14572UB hex functional gate is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. These complementary MOS logic gates find primary use where low power dissipation and/or high noise immunity is desired. The chip contains four inverters, one NOR gate and one NAND gate.

#### **Features**

- Diode Protection on All Inputs
- Single Supply Operation
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- NOR Input Pin Adjacent to V<sub>SS</sub> Pin to Simplify Use As An Inverter
- NAND Input Pin Adjacent to V<sub>DD</sub> Pin to Simplify Use As An
- NOR Output Pin Adjacent to Inverter Input Pin For OR Application
- NAND Output Pin Adjacent to Inverter Input Pin For AND
- Capable of Driving Two Low-Power TTL Loads or One Low-Power Schottky TTL Load over the Rated Temperature
- These Devices are Pb-Free and are RoHS Compliant

#### MAXIMUM RATINGS (Voltages Referenced to V<sub>SS</sub>)

Parameter	Symbol	Value	Unit
DC Supply Voltage Range	$V_{DD}$	-0.5 to +18.0	V
Input or Output Voltage Range (DC or Transient)	V <sub>in</sub> , V <sub>out</sub>	-0.5 to V <sub>DD</sub> + 0.5	<b>V</b>
Input or Output Current (DC or Transient) per Pin	I <sub>in</sub> , I <sub>out</sub>	±10	mA
Power Dissipation, per Package (Note 1)	P <sub>D</sub>	500	mW
Ambient Temperature Range	T <sub>A</sub>	-55 to +125	°C
Storage Temperature Range	T <sub>stg</sub>	-65 to +150	°C
Lead Temperature (8-Second Soldering)	T <sub>L</sub>	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating: Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high-impedance circuit. For proper operation, Vin and Vout should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}$ .

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.

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**MARKING DIAGRAMS** 



PDIP-16 **P SUFFIX CASE 648**  MC14572UBCP O AWLYYWWG <del>իննննն</del>



SOIC-16 **D SUFFIX CASE 751B**  <sup>16</sup>\_\_\_\_\_\_ 14572UBG **AWLYWW** 

= Assembly Location

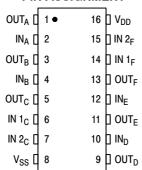
WL = Wafer Lot YY = Year WW = Work Week = Pb-Free Package

## **ORDERING INFORMATION**

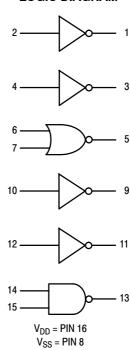
Device	Package	Shipping <sup>†</sup>
MC14572UBCPG	PDIP-16 (Pb-Free)	25 Units / Rail
MC14572UBDG	SOIC-16 (Pb-Free)	48 Units / Rail
MC14572UBDR2G	SOIC-16 (Pb-Free)	2500/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

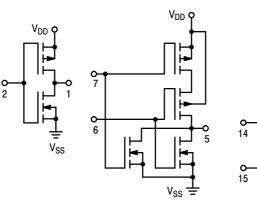
## **PIN ASSIGNMENT**

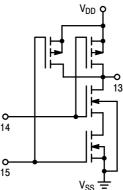


## LOGIC DIAGRAM



## **CIRCUIT SCHEMATIC**





## **ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

LEEGTHIOAE GHAHAGTERIO			- 55°C 25°C 125°C		5°C					
Characteristic	Symbol	V <sub>DD</sub> Vdc	Min	Max	Min	Typ (Note 2)	Max	Min	Max	Unit
Output Voltage "0" Level V <sub>in</sub> = V <sub>DD</sub> or 0	V <sub>OL</sub>	5.0 10 15	- - -	0.05 0.05 0.05	- - -	0 0 0	0.05 0.05 0.05	- - -	0.05 0.05 0.05	Vdc
V <sub>in</sub> = 0 or V <sub>DD</sub> "1" Level	V <sub>OH</sub>	5.0 10 15	4.95 9.95 14.95	- - -	4.95 9.95 14.95	5.0 10 15	- - -	4.95 9.95 14.95	- - -	Vdc
Input Voltage "0" Level (V <sub>O</sub> = 4.5 or 0.5 Vdc) (V <sub>O</sub> = 9.0 or 1.0 Vdc) (V <sub>O</sub> = 13.5 or 1.5 Vdc)	V <sub>IL</sub>	5.0 10 15	- - -	1.0 2.0 2.5	- - -	2.25 4.50 6.75	1.0 2.0 2.5	- - -	1.0 2.0 2.5	Vdc
"1" Level $(V_O = 0.5 \text{ or } 4.5 \text{ Vdc})$ $(V_O = 1.0 \text{ or } 9.0 \text{ Vdc})$ $(V_O = 1.5 \text{ or } 13.5 \text{ Vdc})$	V <sub>IH</sub>	5.0 10 15	4.0 8.0 12.5	- - -	4.0 8.0 12.5	2.75 5.50 8.25	- - -	4.0 8.0 12.5	- - -	Vdc
Output Drive Current (V <sub>OH</sub> = 2.5 Vdc) Source (V <sub>OH</sub> = 4.6 Vdc) (V <sub>OH</sub> = 9.5 Vdc) (V <sub>OH</sub> = 13.5 Vdc)	I <sub>OH</sub>	5.0 5.0 10 15	- 1.2 - 0.25 - 0.62 - 1.8	- - -	- 1.0 - 0.2 - 0.5 - 1.5	- 1.7 - 0.36 - 0.9 - 3.5	- - -	- 0.7 - 0.14 - 0.35 - 1.1	- - -	mAdc
$(V_{OL} = 0.4 \text{ Vdc})$ Sink $(V_{OL} = 0.5 \text{ Vdc})$ $(V_{OL} = 1.5 \text{ Vdc})$	I <sub>OL</sub>	5.0 10 15	0.64 1.6 4.2	- - -	0.51 1.3 3.4	0.88 2.25 8.8	- - -	0.36 0.9 2.4	- - -	mAdc
Input Current	l <sub>in</sub>	15	_	±0.1	_	±0.00001	±0.1	_	±1.0	μAdc
Input Capacitance (V <sub>in</sub> = 0)	C <sub>in</sub>	-	_	ı	_	5.0	7.5	_	-	pF
Quiescent Current (Per Package)	I <sub>DD</sub>	5.0 10 15	- - -	0.25 0.5 1.0	- - -	0.0005 0.0010 0.0015	0.25 0.5 1.0	- - -	7.5 15 30	μAdc
Total Supply Current (Notes 3, 4) (Dynamic plus Quiescent, Per Package) (C <sub>L</sub> = 50 pF on all outputs, all buffers switching)	I <sub>T</sub>	5.0 10 15			$I_{T} = (3)$	.89 μA/kHz) .80 μA/kHz) .68 μA/kHz)	f + I <sub>DD</sub>			μAdc

Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
 The formulas given are for the typical characteristics only at 25°C.
 To calculate total supply current at loads other than 50 pF: I<sub>T</sub>(C<sub>L</sub>) = I<sub>T</sub>(50 pF) + (C<sub>L</sub> – 50) Vfk where: I<sub>T</sub> is in μA (per package), C<sub>L</sub> in pF, V = (V<sub>DD</sub> – V<sub>SS</sub>) in volts, f in kHz is input frequency, and k = 0.006.

## **SWITCHING CHARACTERISTICS** (Type 5) ( $C_L = 50 \text{ pF}, T_A = 25^{\circ}C$ )

Characteristic	Symbol	V <sub>DD</sub>	Min	Typ (Note 6)	Max	Unit
Output Rise Time $t_{TLH} = (3.0 \text{ ns/pF}) \text{ C}_L + 30 \text{ ns} \\ t_{TLH} = (1.5 \text{ ns/pF}) \text{ C}_L + 15 \text{ ns} \\ t_{TLH} = (1.1 \text{ ns/pF}) \text{ C}_L + 10 \text{ ns}$	t <sub>TLH</sub>	5.0 10 15	- - -	180 90 65	360 180 130	ns
Output Fall Time $t_{THL} = (1.5 \text{ ns/pF}) \text{ C}_L + 25 \text{ ns} \\ t_{THL} = (0.75 \text{ ns/pF}) \text{ C}_L + 12.5 \text{ ns} \\ t_{THL} = (0.55 \text{ ns/pF}) \text{ C}_L + 9.5 \text{ ns} \\ \end{cases}$	t <sub>THL</sub>	5.0 10 15	- - -	100 50 40	200 100 80	ns
Propagation Delay Time $t_{PLH}, t_{PHL} = (1.7 \text{ ns/pF}) C_L + 5 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.66 \text{ ns/pF}) C_L + 17 \text{ ns}$ $t_{PLH}, t_{PHL} = (0.5 \text{ ns/pF}) C_L + 15 \text{ ns}$	t <sub>PLH</sub> , t <sub>PHL</sub>	5.0 10 15	- - -	90 50 40	180 100 80	ns

- 5. The formulas given are for the typical characteristics only at 25°C.
  6. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.

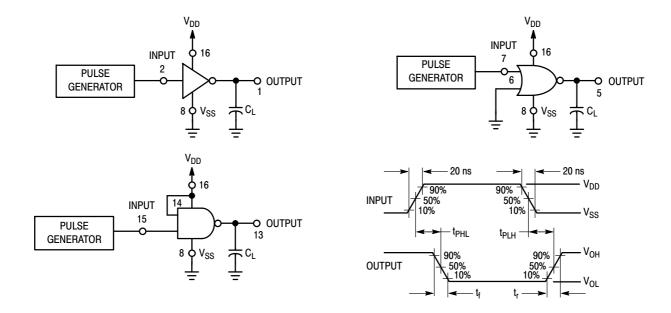
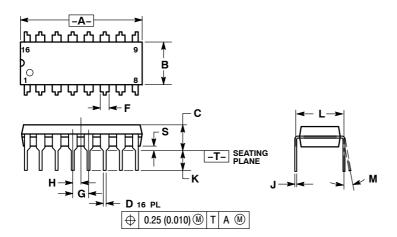


Figure 1. Switching Time Test Circuits and Waveforms

## **PACKAGE DIMENSIONS**

## PDIP-16 CASE 648-08 **ISSUE T**

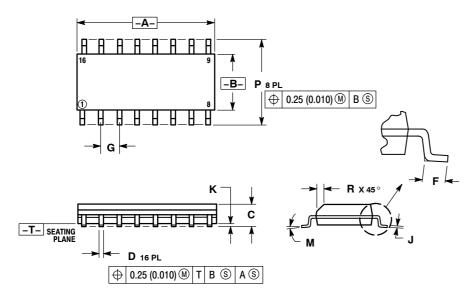


- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL.

	INC	HES	MILLIN	IETERS	
DIM	MIN	IIN MAX MIN		MAX	
Α	0.740	0.770	18.80	19.55	
В	0.250	0.270	6.35	6.85	
С	0.145	0.175	3.69	4.44	
D	0.015	0.021	0.39	0.53	
F	0.040	0.70	1.02	1.77	
G	0.100 BSC		2.54 BSC		
Н	0.050	BSC	1.27	BSC	
J	0.008	0.015	0.21	0.38	
Κ	0.110	0.130	2.80	3.30	
L	0.295	0.305	7.50	7.74	
М	0°	10 °	0 °	10 °	
S	0.020	0.040	0.51	1.01	

#### PACKAGE DIMENSIONS

### SOIC-16 CASE 751B-05 ISSUE K



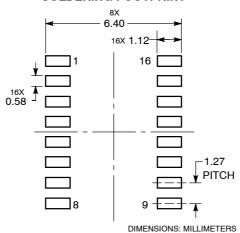
#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMETER.
- 3. DIMENSIONS A AND B DO NOT INCLUDE MOLD
- PROTRUSION.

  4. MAXIMUM MOLD PROTRUSION 0.15 (0.006) PER SIDE.
- 5. DIMENSION D DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.127 (0.005) TOTAL IN EXCESS OF THE D DIMENSION AT MAXIMUM MATERIAL CONDITION.

	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	9.80	10.00	0.386	0.393	
В	3.80	4.00	0.150	0.157	
С	1.35	1.75	0.054	0.068	
D	0.35	0.49	0.014	0.019	
F	0.40	1.25	0.016	0.049	
G	1.27	1.27 BSC		BSC	
J	0.19	0.25	0.008	0.009	
K	0.10	0.25	0.004	0.009	
M	0 °	7°	0°	7°	
Р	5.80	6.20	0.229	0.244	
R	0.25	0.50	0.010	0.019	

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